



PK171 (v1.3) November 18,
2011

100% Material Declaration Data Sheet for VQ44 Package

Average Weight: 0.2669 g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.003341	1.252
	Silicon (Si)	7440-21-3	100.00		0.003341	
Die Attach					0.000921	0.345
	Silver (Ag)	7440-22-4	72.00		0.000663	
	Epoxy (EP)	254-641-8	7.00		0.000064	
	Aliphatic acid anhydride	Trade Secret	7.00		0.000064	
	2,6-Diglycidyl phenyl allyl ether oligomer	417-470-1	5.00		0.000046	
	Epoxy derivative	Trade Secret	3.00		0.000028	
	Hexahydro-4-methylphthalic anhydride	243-072-0	3.00		0.000028	
Mold Compound					0.181160	67.872
	Epoxy Resin	Trade secret	7.00		0.012681	
	Phenol Resin	Trade secret	5.00		0.009058	
	Carbon Black	1333-86-4	0.30		0.000543	
	Fused Silica	60676-86-0	87.70		0.158877	
Leadframe					0.076600	28.698
	Copper (Cu)	7440-50-8	98.28		0.075282	
	Chromium (Cr)	7440-47-3	0.25		0.000192	
	Tin (Sn)	7440-31-5	0.25		0.000192	
	Zinc (Zn)	7440-66-6	0.22		0.000169	
	Silver (Ag)	7440-22-4	1.00		0.000766	
Solder Plating					0.003502	1.312
	Tin (Sn)	7440-31-5	85.00		0.002977	
	Lead (Pb)	7439-92-1	15.00		0.000525	
Gold Wire					0.001389	0.520
	Gold (Au)	7440-57-5	99.00		0.001375	
	Palladium	7440-05-3	1.00		0.000014	

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
03/16/06	1.0	Initial Xilinx release.
08/04/06	1.1	100% Material Declaration
10/05/06	1.2	Updated Component descriptions
11/18/11	1.3	Updated Component weights and descriptions

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